V1 — 06/26

Qualitek 775-2 Water Soluble Solder Paste Sn62/Pb36/Ag2

SKU: 390-775 | Sizes: Sn62/Pb36/Ag2 - 500gm JAR, Sn62/Pb36/Ag2 - 500gm CART

Features & Benefits

- **Alloy composition**: 62% Tin, 36% Lead, 2% Silver (Sn62/Pb36/Ag2)
- **Halogen-free** for cleaner and environmentally friendly soldering
- **Non-hygroscopic** to prevent moisture absorption
- **Slump-resistant** for stable performance during soldering
- **High tack force** for strong adhesion
- **Type 3 particle size** (25-45µm) for fine-pitch applications
- **Flux residues** easily removed with warm DI water (60°C)
- **Pleasant odour** for a more comfortable working environment
- **Extended stencil life** for long-lasting use
- Ideal for surface mount and electronic assembly applications
- **Sample requests available for registered users**
- Featuring a tin (62%), lead (36%), and silver (2%) alloy, this paste ensures excellent soldering performance with a tack time of over 12 hours, thanks to its low-volatility solvent system

About the Qualitek 775-2 Water Soluble Solder Paste Sn62/Pb36/Ag2

Qualitek 775-2 Water Soluble Solder Paste (Sn62/Pb36/Ag2) is a high-performance, halogen-free, and slump-resistant paste designed for surface mount and electronic assembly applications.
Featuring a tin (62%), lead (36%), and silver (2%) alloy, this paste ensures excellent soldering performance with a tack time of over 12 hours, thanks to its low-volatility solvent system.
The flux residues are easily removed using warm deionised water (60°C), ensuring a clean finish. With Type 3 particle sizes (25-45µm), it offers extended stencil life, high tack force, and resistance to slump, making it perfect for precise, efficient soldering.

Specifications

Property	Detail
Application	ESD-protected areas, electronics mfg, cleanrooms